


APPLICATION DATA SHEET

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Title of Invention	[METHOD OF ENHANCING THE ADHESION BETWEEN PHOTORESIST LAYER AND SUBSTRATE AND BUMPING PROCESS]		
Application Type : regular, utility Attorney Docket Number : 11577-US-PA			
Correspondence address: Customer Number: 31561 			
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Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Min-Lung Family Name: Huang Residence: City of Residence: Kaohsiung Country of Residence: TW Address-1 of Mailing Address: 10F., No. 8, Alley 2, Lane 33, Ting-yung St., Address-2 of Mailing Address: San-min Chu City of Mailing Address: Kaohsiung State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address: TW Phone: Fax: E-mail:			
Attorney Information: practitioner(s) at Customer Number:			

31561



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